

ABSTRACT

Provided is a semiconductor device including: a first active portion; an isolation region on a side surface of the first active portion; and a bit line connected to the first active portion, wherein the first active portion includes a first region in contact with the isolation region and a second region extending upwardly from the first region, wherein the second region is spaced apart from the isolation region, and wherein the bit line includes: a line portion extending in a first horizontal direction; and a contact portion below the line portion, wherein the contact portion is connected to the second region of the first active portion.

FIG. 2B